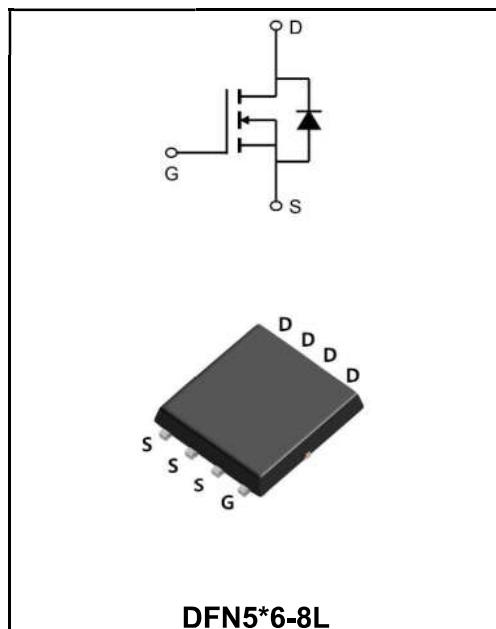


**60V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	130A
$V_{DSS}$	60V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 3.0mΩ (Type: 2.5 mΩ)


**Features**

- ◆ Low RDS(on) & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity or Invertors
- ◆ YFW-SGT technology

**Applications**

- ◆ Consumer electronic power supply Motor control
- ◆ Synchronous-rectification Isolated DC
- ◆ Synchronous-rectification applications

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFWG130N06NF	DFN5*6-8L	YFW 130N06NF XXXXX	5000PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

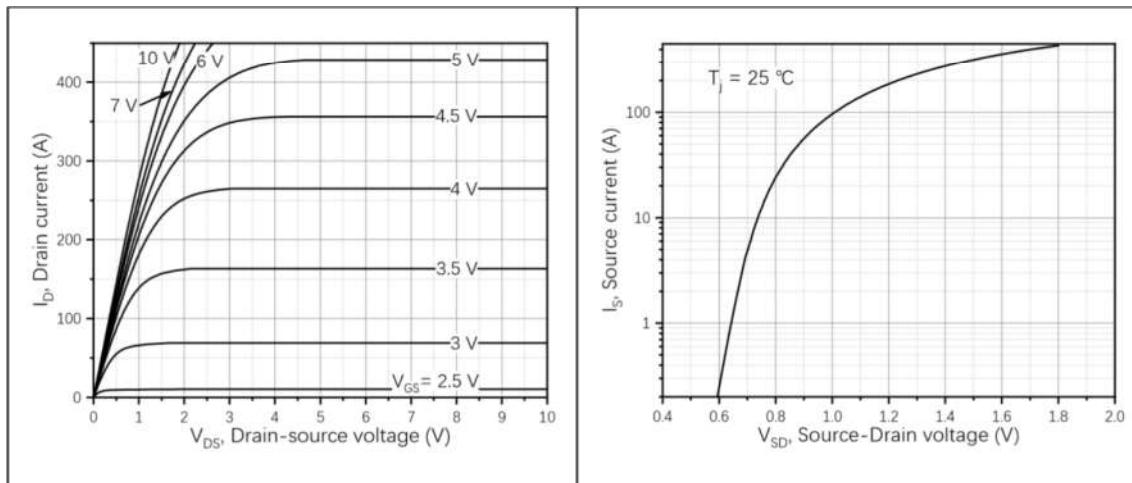
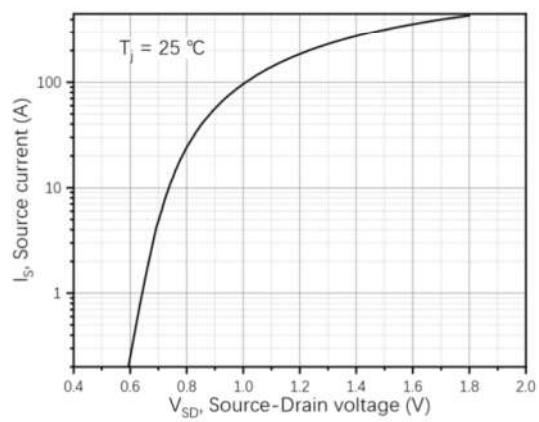
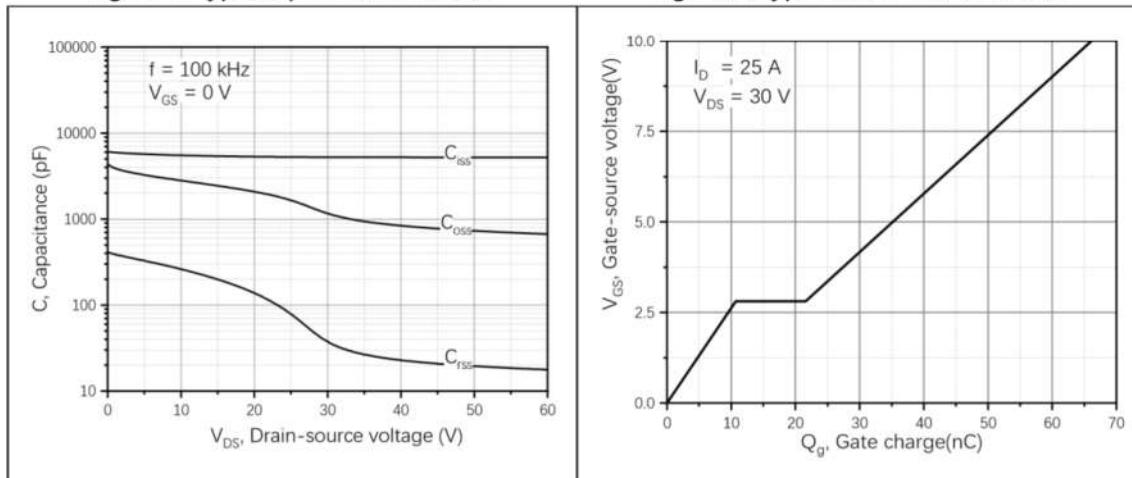
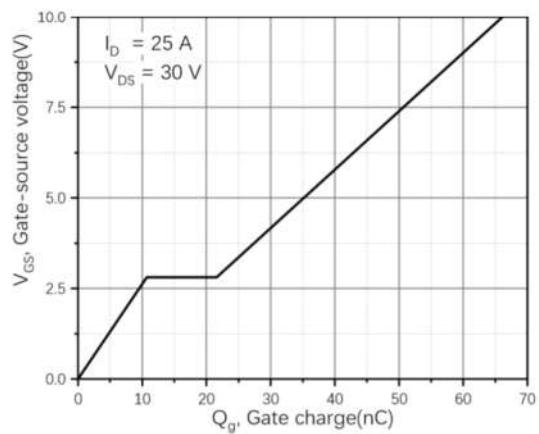
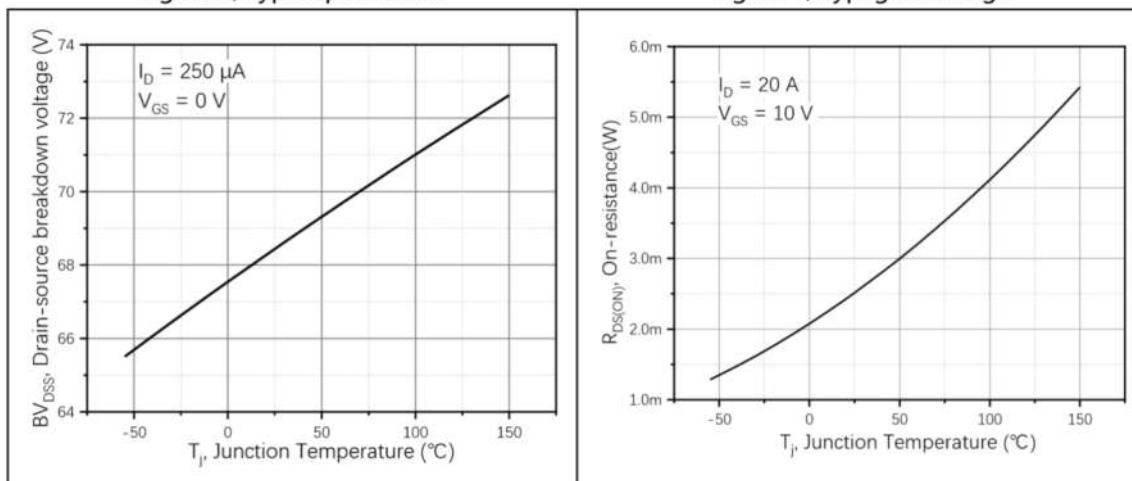
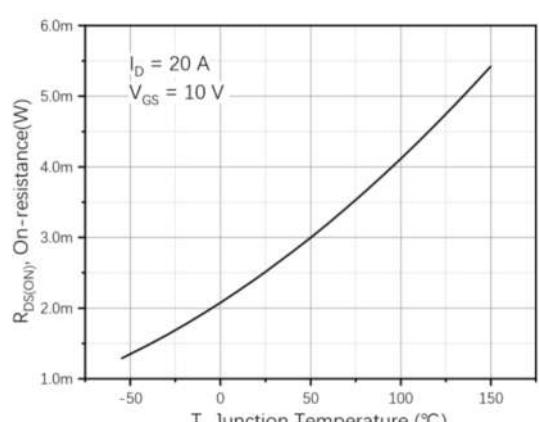
Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current <sup>1)</sup>	$I_D$	130	A
Pulsed drain current <sup>2)</sup>	$I_{D, \text{pulse}}$	390	A
Power dissipation <sup>3)</sup>	$P_D$	140	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	80	mJ
Operation and storage temperature	$T_{STG}, T_J$	-55 to +150	°C
Thermal Resistance Junction-Case	$R_{\theta JC}$	0.89	°C/W
Thermal Resistance, Junction-to-Ambient <sup>4)</sup>	$R_{\theta JA}$	62	°C/W

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	60	-	-	V
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.0	-	2.5	V
Drain-source on-state resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	R <sub>DS(ON)</sub>	-	2.5	3.0	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		-	3.5	4.5	
Gate-Source Leakage Current	V <sub>GS</sub> =20V	I <sub>GSS</sub>	-	-	100	nA
	V <sub>GS</sub> =20V		-	-	-100	
Drain -Source Leakage Current	V <sub>DS</sub> =60V , V <sub>GS</sub> =0V	I <sub>DSS</sub>	-	-	1	μA
Input Capacitance	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=100KHz	C <sub>iss</sub>	-	5377	-	pF
Output Capacitance		C <sub>oss</sub>	-	1666	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	77.7	-	
Turn-on delay time	V <sub>GS</sub> =10V V <sub>DD</sub> =30V R <sub>G</sub> =2Ω I <sub>D</sub> =25A	t <sub>d(on)</sub>	-	22.5	-	ns
Rise Time		T <sub>r</sub>	-	6.7	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	80.3	-	
Fall Time		t <sub>f</sub>	-	26.8	-	
Gate-source charge	I <sub>D</sub> =25A V <sub>DS</sub> =50V V <sub>GS</sub> =10V	Q <sub>g</sub>	-	10.7	-	nC
Gate-Drain Charge		Q <sub>gd</sub>	-	10.9	-	
Gate plateau voltage		V <sub>plateau</sub>	-	2.9	-	
Diode forward current	V <sub>GS</sub> <V <sub>th</sub>	I <sub>s</sub>	-	-	130	A
Pulsed source current		I <sub>SP</sub>	-	-	390	
Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>s</sub> =20A	V <sub>SD</sub>	-	-	1.3	V
Reverse Recovery Time	I <sub>s</sub> =25A , dI/dt=100A/μs ,	t <sub>rr</sub>	-	68.3	-	ns
Reverse Recovery Charge		Q <sub>rr</sub>	-	73.0	-	
Peak reverse recovery current		I <sub>rrm</sub>	-	1.9	-	

**Note**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with Ta=25 °C.
- 5) VDD=50 V, RG=25 Ω, L=0.3 mH, starting Tj=25 °C.

**Ratings and Characteristic Curves**

**Figure 1, Typ. output characteristics**

**Figure 2, Typ. transfer characteristics**

**Figure 3, Typ. capacitances**

**Figure 4, Typ. gate charge**

**Figure 5, Drain-source breakdown voltage**

**Figure 6, Drain-source on-state resistance**

**Ratings and Characteristic Curves**

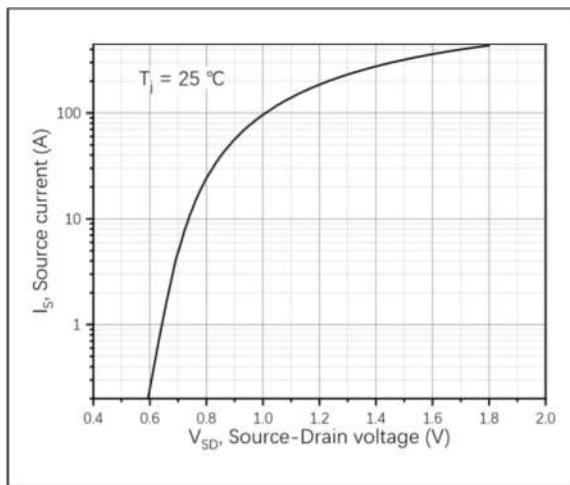


Figure 7, Forward characteristic of body diode

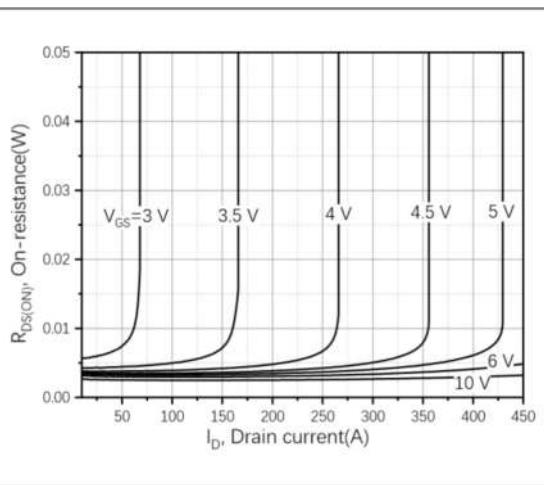


Figure 8, Drain-source on-state resistance

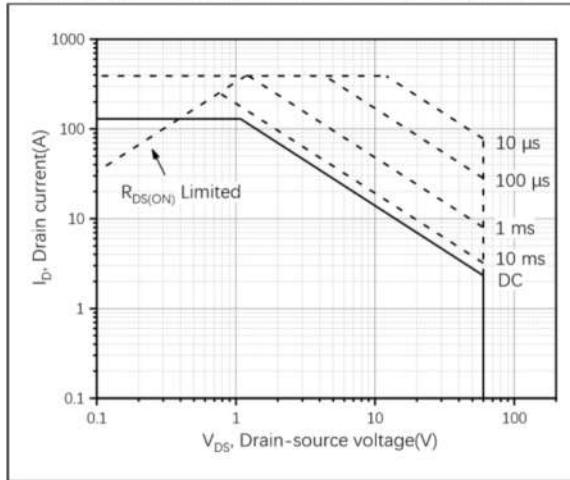
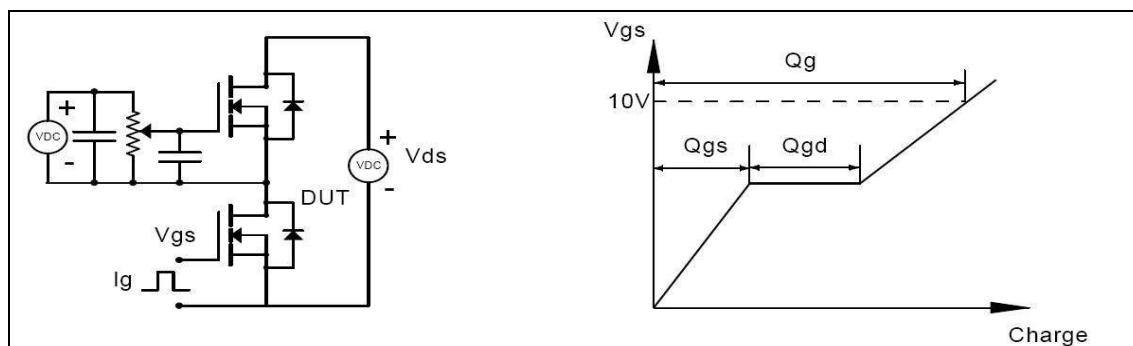
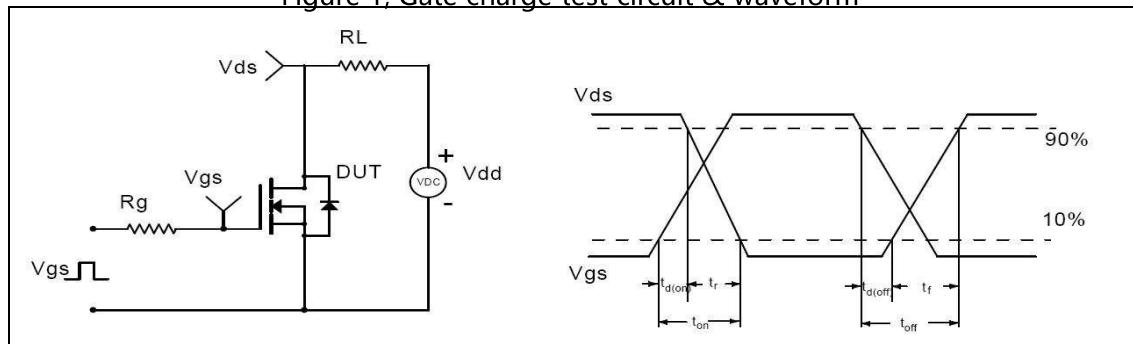
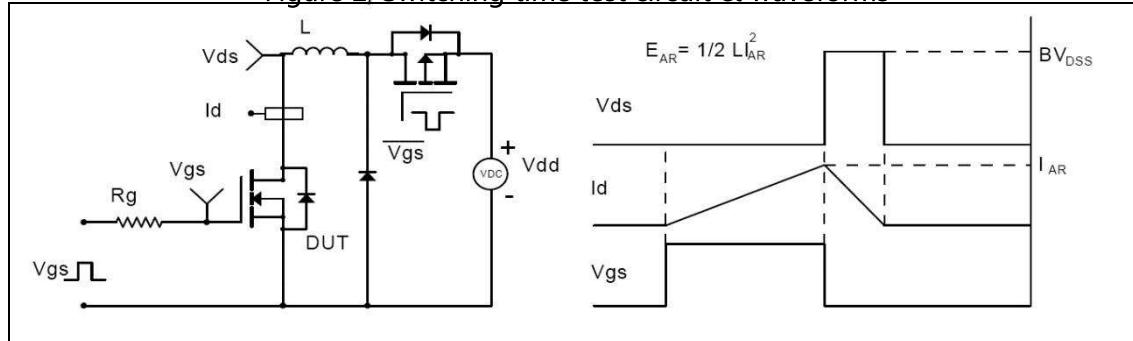
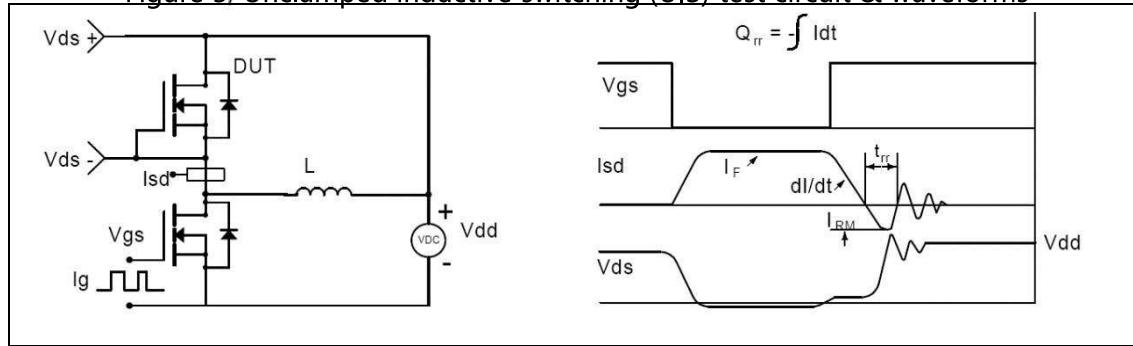
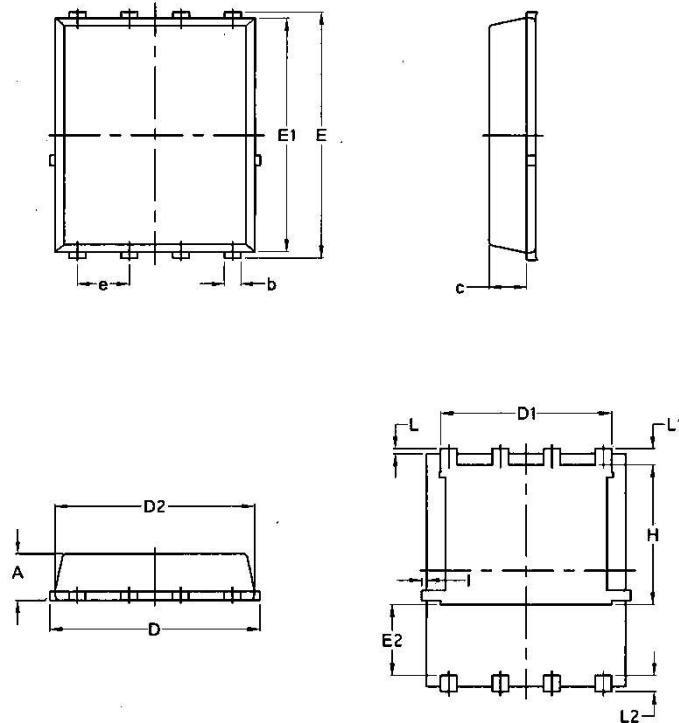


Figure 9, Safe operation area  $T_C=25 \text{ } ^\circ\text{C}$

**Ratings and Characteristic Curves**

**Figure 1, Gate charge test circuit & waveform**

**Figure 2, Switching time test circuit & waveforms**

**Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms**

**Figure 4, Diode reverse recovery test circuit & waveforms**

**Package Outline Dimensions Millimeters**
**DFN5\*6-8L**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070